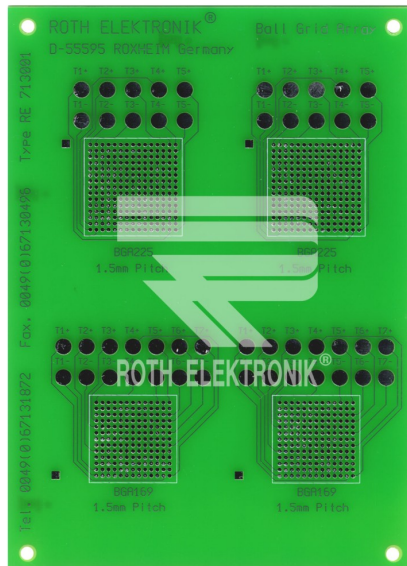


PCB for Pick and Place Soldering Practice for BGA 169 and 225



RE713001-LF



- PCB for solder practices pick-and-place for BGA 169 and 225 grid 1.50 mm including daisychain test points
- introduction into trend-setting technology
- EPOXY resin FR4 1.50 mm single-sided 35 µm CU
- solder side hot air leveling coated (HAL-leadfree), solder stop mask and additional print

BGA 169 : 2 x
BGA 225 : 2 x

- size 100 x 140 mm